What is claimed is:

1. A laminated polishing pad for chemical mechanical polishing, the polishing pad comprising:

a base layer;

a polishing layer overlying the base layer; and

a hot-melt adhesive layer, interposed between the base layer and the polishing layer, the adhesive layer bonding the base layer to the polishing layer, wherein a Tpeel strength of the bonding is at least greater than 40 Newtons at 305 mm/min.

2. The polishing pad of claim 1, wherein the Tpeel strength of said bonding is at least greater than 68 Newtons at 305 mm/min.

3. The polishing pad of claim 1, wherein the base layer is selected from the group consisting of: polymer impregnated felts or filled polymer sheets.

4. The polishing pad of claim 1, wherein the polishing layer is selected from the group consisting of: polymer impregnated felts, poromerics, filled polymer sheets, and unfilled textured polymers.

5. The polishing pad of claim 1, wherein the hot-melt adhesive is selected from the group consisting of: polyolefins, ethylene vinyl acetate, polyamides, polyesters, polyurethanes, polyvinyl chloride and epoxies.

6. The polishing pad of claim 1, wherein the hot-melt adhesive layer has a thickness in the range of 2.54×10^{-4} cm to 6.35×10^{-2} cm.

7. A laminated polishing pad for chemical mechanical polishing, the polishing pad comprising:

a base layer having a first opening;

a polishing layer overlying the base layer, the polishing layer having a second opening wider than the first opening;

a window formed in the second opening; and

a hot-melt adhesive layer, interposed between the base layer, the polishing layer and the window, the adhesive layer bonding the base layer to the polishing layer and the window, wherein a Tpeel strength of the bonding is at least greater than 40 Newtons at 305 mm/min.

8. A laminated polishing pad for chemical mechanical polishing, the polishing pad comprising:

a polymer impregnated felt base layer having a first opening;

a filled polymer sheet polishing layer overlying the base layer, the polishing layer having a second opening wider than the first opening;

a window formed in the second opening; and

a hot-melt adhesive layer, interposed between the base layer, the polishing layer and the window, the adhesive layer bonding the base layer to the polishing layer and the window, wherein a Tpeel strength of the bonding is at least greater than 40 Newtons at 305 mm/min.

9. A method of forming a laminated polishing pad for chemical mechanical polishing, the method comprising:

providing a base layer;

providing a polishing layer;

depositing a hot-melt adhesive on the base layer or the polishing layer;

interposing the base layer to the polishing layer with the hot-melt adhesive before the hot-melt adhesive sets; and

setting the hot-melt adhesive to bond the base layer to the polishing layer, wherein a Tpeel strength of the bond is at least greater than 40 Newtons at 305 mm/min.

10. A method of forming a laminated polishing pad for chemical mechanical polishing, the method comprising:

providing a base layer having a first opening;

providing a polishing layer having a second opening wider than the first opening;

depositing a hot-melt adhesive on the base layer;

interposing the base layer to the polishing layer with the hot-melt adhesive before the hot-melt adhesive sets;

providing a window in the second opening and on the hot-melt adhesive before the hot-melt adhesive sets;and

setting the hot-melt adhesive to bond the base layer to the polishing layer and the window, wherein a Tpeel strength of the bond is at least greater than 40 Newtons at 305 mm/min.